## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE REQUEST FOR FILING NEW UTILITY PATENT APPLICATION UNDER 37 CFR § 1.53(b)

(Docket No. 207.010-US)



To: Commission for Patents
Mail Stop Patent Application
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Transmitted herewith for filing under 37 C.F.R. §1.53(b) is a new utility patent application for:

Title: Anti-Stiction Technique for Thin Film and Wafer-Bonded Encapsulated Microelectromechanical Systems

Inventors: Lutz & Partridge

- 1. To effect the above-requested filing, attached hereto is:
  - 1. Specification, Claims, and Abstract (49 pages)
  - 2. One (1) set of formal drawings having 44 sheets
  - 3. One (1) executed Declarations and Powers of Attorney (2 pages)
  - 4. Check (\$1,612.00) (see below for fee calculation)
- 2. Kindly address all communications with respect to this application to:

Neil A. Steinberg Steinberg & Whitt, LLP 2665 Marine Way, Suite 1150 Mountain View, CA 94043

Telephone: 650-968-8079 Facsimile: 650-968-8102

3.	The fee to effect the above-referenced filing is calculated as follows:		
	Basic Fee\$_770.00		
	Additional Fees:		
	:	Surcharge - more than 20 total cl	aims (42 additional)\$ <u>756.00</u>
	;	Surcharge - more than 3 indepen	dent claims (1 additional)\$ <u>86.00</u>
	;	Surcharge - multiple dependent c	laims\$ <u>- 0 -</u>
	Total	otal Filing Fee\$ 1,612.00	
4.	Payment of the Total Filing Fee is as follows:		ollows:
	[XX]		nissioner of Patents and Trademarks, in the das payment of the Total Filing Fee.
	[]		No. 50-0763 in the amount of \$ to ate copy of this sheet is enclosed.
	[XX]	The Commissioner is hereby authorized to charge any fees that may be required, or credit any overpayment to Deposit Acc. No. 50-0763. A duplicate copy of this sheet is enclosed.	
Date: October 31, 2003		er 31, 2003	Respectfully submitted,  Neil A. Steinberg Reg. No. 34,735 650-968-8079

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

(Case No. 207.008-US)

In the Application of: Lutz et al.

Filed: October 31, 2003

Serial No: To Be Assigned

Title: Anti-Stiction Technique for Thin Film and Wafer-Bonded Encapsulated

Microelectromechanical Systems

Mail Stop Patent Application Commissioner of Patents P.O. Box 1450 Alexandria, VA 22313-1450

## CERTIFICATE OF MAILING BY "EXPRESS MAIL"

"Express Mail" Mailing Label No. ER452406360US

Date of Deposit: October 31, 2003

I hereby certify that the attached: 1) New Utility Patent Application Transmittal for Filing under 37 CFR §1.53(b) (2 pages + 1 copy thereof), 2) Application (49 pages + 44 sheets of drawings), 3) Executed Declaration and Power of Attorney (2 pages total), and 4) Check (\$1,612.00) is/are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" Service under 37 C.F.R. 1.10 on the date indicated above and is addressed to the Commissioner of Patents, Mail Stop Patent Application, P.O. Box 1450, Alexandria, VA 22313-1450.

Signature

Print Name of Person Mailing